

4/26/00

05-16-2000

ASSIGNMENT RECORDATION FOR



101357049

April 24, 2000
Attorney Dkt. 5649-811

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Young-Sub Yu
Hyun-Bo Shin

2. Name and address of receiving party(ies):

Samsung Electronics Co., Ltd.
416 Maetan-dong, Paldal-gu
Suwon-city, Kyungki-do
REPUBLIC OF KOREA

APR 25 PM 9:23
OPR/FINANCE

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:

- Assignment
- Merger
- Security Agreement
- Change of Name
- Other _____

Execution Date: April 18, 2000

Additional name(s) & address(es) attached? Yes No

4. Application Serial No. 09/526,850 Filed March 16, 2000

If this document is being filed together with a new application, the execution date of the application is: _____

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Grant J. Scott
Myers Bigel Sibley & Sajovec
P. O. Box 37428
Raleigh NC 27627

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00
 Enclosed
 Authorized to be charged to deposit account

8. Deposit account number: 50-0220

DO NOT USE THIS SPACE

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9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document

Grant J. Scott #36,925

Name of Person Signing

Signature

April 24, 2000

Date

Total number of pages including cover sheet, attachments and document: 3

ASSIGNMENT

THIS ASSIGNMENT, made by us, **Young-Sub Yu**, citizen of the Republic of Korea, residing at 11-102, WoosungApt., Jisan-dong, Pyoungtaek-shi, Kyunggi-do, Republic of Korea; and **Hyun-Bo Shin**, citizen of the Republic of Korea, residing at 109-201, HansungApt., 698-2, Poongdukcheon-ri, Suji-eub, Yongin-shi, Kyunggi-do, Republic of Korea;

WITNESSETH: That,

WHEREAS, we are the joint inventors of certain new and useful improvements in **CYLINDRICAL CAPACITOR HAVING HSG SILICONS ON ITS INNER SURFACES AND METHOD FOR FABRICATING THEREOF** for which an application for United States Letters Patent has been filed, or is being filed concurrently, in the United States Patent and Trademark Office. We hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. 09/526,850, filed March 16, 2000) the filing date and application number of said application when known or to file this Assignment concurrently with the application, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal place of business at 416 Maetan-dong, Paldal-gu, Suwon-City, Kyungki-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to bind our heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, we have hereunto set our hands and seals on this 18th day of April, 2000.

Young-Sub Yu
Young-Sub Yu

Hyun Bo Shin
Hyun-Bo Shin

Witnessed by:

Date: _____

Date: _____